Technical Information - BoLink Thermoplastic staking

Instructions for mounting a circuit board in the BoLink by Thermoplastic staking.

Test setup:

The basis for the experimental setup is a hand lever built-in heating device (KVT-Bielefeld).
The heating element with a flat head ø3.6mm is heated to 160°C.
The device is adjusted in such a way that the protruding dome is pressed down and expanded in a defined manner, thereby creating a form-fit connection between the PCB and the housing.
The lower part of the BoLink should be accommodated within the recessed membrane area and rest on it.

(a transparent PC board was used as a circuit board dummy)

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Result:

Thermoplastic staking deforms the domes to the following dimensions with a board thickness of 1.6 mm:

Residual height above the board: 0.8mm

Diameter ø2.8 to ø3mm

The circuit board must not rattle after installation.

Please note!

All technical information stated here is provided to the best of our knowledge, but nonetheless in no way exempts the user from the duty to verify the suitability of the product for the intended application.

Status 23.05.2024 - Subject to technical changes